



7th IEEE Int. Workshop on Hot Topics in 3D - *Hot 3D*

Seattle, USA, July 11, 2016
(in conjunction with ICME 2016)

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The 3D research community is at a potentially revolutionary point. From one side, 3D display technology is at the verge of becoming widespread and reasonably priced, and that includes autostereoscopic, light-field, and holographic displays. From another direction, increases in computational power – including powerful GPUs - have allowed an ever-increasing realism in 3D scene generation. 3D audio is also tightly integrated with 3D environments, including 5.1 (and higher) and even 3D sound field reproduction. Finally, new devices to capture omnidirectional content, depth, light-field and point cloud coupled with new 3D analysis and synthetic algorithms are appearing, paving the road for new approaches to produce, process and display 3D content. The recent trends in AR/VR displays have further accelerated research and innovation in 3D. Haptic systems are also being tightly integrated with 3D systems. Quality evaluation of 3D systems itself is of great importance, and is also showing fast progress.

All these factors together create the “perfect storm”: an environment prone for an explosion of related technology and applications, with a speed of development that will not fit in the (slower) cycle of traditional conferences and journals. In other words, while appropriate venues for presenting research at advanced stages is plentiful, the 3D Multimedia community lacks an appropriate venue for receiving feedback during early or initial stages of the development of radical or potentially disruptive technology. This is exactly the void that Hot3D tries to fill.

After the enormous success of the previous Hot3D in Singapore (2010), Barcelona (2011), Melbourne (2012), San Jose (2013), Chengdu (2014), and Torino (2015), Hot3D 2016 is again expected to represent a premier venue, providing an environment for lively discussion of early-stage, potentially disruptive research.

SCOPE AND FORMAT

Papers in all areas of Multimedia 3D are solicited. Early stage or preliminary results from potentially disruptive technology is particularly encouraged. Full papers (up to 6 pages) will be published in the ICME proceedings.

Additionally, and maybe most importantly, position papers are solicited for short presentation and discussion of preliminary work or ideas. Submit a proposal of up to 2 pages, with a decision expected up to 3 weeks after submission.

The 1-day workshop will be co-located with ICME, the flagship multimedia conference sponsored by four IEEE societies. The workshop will be a unique opportunity to interact with other researchers working on 3D Multimedia. With an environment designed to facilitate discussion and feedback in early stage research, as well as forge new collaboration, this is an event not to be missed.

IMPORTANT DATES

Submit **Regular Paper** (up to 6 pages) by: **March 18, 2016**

Notification of Regular Paper Acceptance: April 22, 2016

Camera-Ready Paper Due: May 13, 2016

Submit **Position Paper** (up to 2 pages) Submission: **ASAP, up to May 15, 2016**

Notification of (Position Paper) Accept.: April 16, or 3 weeks after submission.

FOR MORE INFORMATION, PLEASE VISIT:

www.hot3D.org



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